

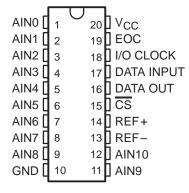
## 12-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

- 12-Bit-Resolution A/D Converter
- 10-μs Conversion Time Over Operating Temperature
- 11 Analog Input Channels
- 3 Built-In Self-Test Modes
- Inherent Sample-and-Hold Function
- Linearity Error . . . ±1 LSB Max
- On-Chip System Clock
- End-of-Conversion Output
- Unipolar or Bipolar Output Operation (Signed Binary With Respect to 1/2 the Applied Voltage Reference)
- Programmable MSB or LSB First
- Programmable Power Down
- Programmable Output Data Length
- CMOS Technology
- Application Report Available<sup>†</sup>

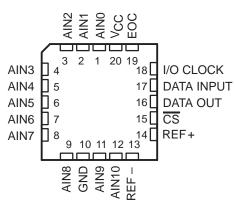
### description

The TLC2543C and TLC2543I are 12-bit, switched-capacitor, successive-approximation, analog-to-digital converters. Each device has three control inputs [chip select ( $\overline{CS}$ ), the input-output clock (I/O CLOCK), and the address input (DATA INPUT)] and is designed for communication with the serial port of a host processor or peripheral through a serial 3-state output. The device allows high-speed data transfers from the host.

### DB, DW, J, OR N PACKAGE (TOP VIEW)



### FK OR FN PACKAGE (TOP VIEW)

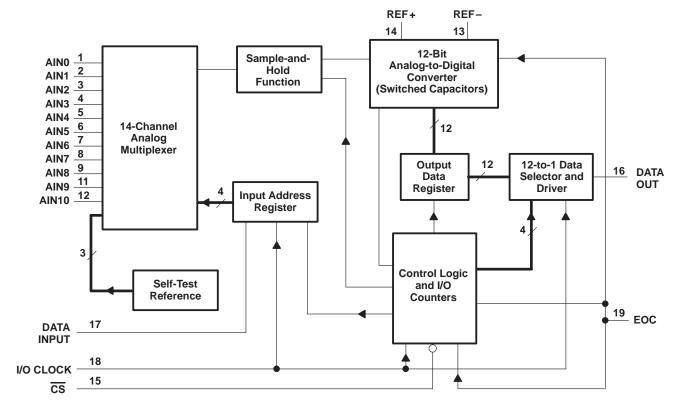


In addition to the high-speed converter and versatile control capability, the device has an on-chip 14-channel multiplexer that can select any one of 11 inputs or any one of three internal self-test voltages. The sample-and-hold function is automatic. At the end of conversion, the end-of-conversion (EOC) output goes high to indicate that conversion is complete. The converter incorporated in the device features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating temperature range.

The TLC2543C is characterized for operation from  $T_A = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ . The TLC2543I is characterized for operation from  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ . The TLC2543M is characterized for operation from  $T_A = -55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .



### functional block diagram





### **Terminal Functions**

TERMINAL			DECEDIDATION				
NAME	NO.	1/0	DESCRIPTION				
AIN0 – AIN10	1-9, 11, 12	I	Analog input. These 11 analog-signal inputs are internally multiplexed. The driving source impedance should be less than or equal to 50 $\Omega$ for 4.1-MHz I/O CLOCK operation and be capable of slewing the analog input voltage into a capacitance of 60 pF.				
<u>cs</u>	15	I	Chip select. A high-to-low transition on $\overline{\text{CS}}$ resets the internal counters and controls and enables DATA OUT, DATA INPUT, and I/O CLOCK. A low-to-high transition disables DATA INPUT and I/O CLOCK within a setup time.				
DATA INPUT	17	I	Serial-data input. A 4-bit serial address selects the desired analog input or test voltage to be converted next. The serial data is presented with the MSB first and is shifted in on the first four rising edges of I/O CLOCK. After the four address bits are read into the address register, I/O CLOCK clocks the remaining bits in order.				
DATA OUT	16	0	The 3-state serial output for the A/D conversion result. DATA OUT is in the high-impedance state when $\overline{CS}$ is high and active when $\overline{CS}$ is low. With a valid $\overline{CS}$ , DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB/LSB <sup>†</sup> value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next MSB/LSB, and the remaining bits are shifted out in order.				
EOC	19	0	End of conversion. EOC goes from a high to a low logic level after the falling edge of the last I/O CLOCK and remains low until the conversion is complete and the data is ready for transfer.				
GND	10		Ground. GND is the ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.				
I/O CLOCK	18	ı	<ol> <li>Input/output clock. I/O CLOCK receives the serial input and performs the following four functions:</li> <li>It clocks the eight input data bits into the input data register on the first eight rising edges of I/O CLOCK with the multiplexer address available after the fourth rising edge.</li> <li>On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplexer input begins charging the capacitor array and continues to do so until the last falling edge of the I/O CLOCK.</li> <li>It shifts the 11 remaining bits of the previous conversion data out on DATA OUT. Data changes on the falling edge of I/O CLOCK.</li> <li>It transfers control of the conversion to the internal state controller on the falling edge of the last I/O CLOCK.</li> </ol>				
REF+	14	I	Positive reference voltage The upper reference voltage value (nominally V <sub>CC</sub> ) is applied to REF+. The maximum input voltage range is determined by the difference between the voltage applied to this terminal and the voltage applied to the REF – terminal.				
REF-	13	ı	Negative reference voltage. The lower reference voltage value (nominally ground) is applied to REF				
Vcc	20		Positive supply voltage				

<sup>†</sup> MSB/LSB = Most significant bit /least significant bit



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.5 V to 6.5 V
Input voltage range, V <sub>I</sub> (any input)	$\dots$ -0.3 V to V <sub>CC</sub> + 0.3 V
Output voltage range, V <sub>O</sub>	$-0.3 \text{ V to V}_{CC} + 0.3 \text{ V}$
Positive reference voltage, V <sub>ref+</sub>	V <sub>CC</sub> + 0.1 V
Negative reference voltage, V <sub>ref</sub>	
Peak input current, I <sub>I</sub> (any input)	±20 mA
Peak total input current, I <sub>I</sub> (all inputs)	±30 mA
Operating free-air temperature range, T <sub>A</sub> : TLC2543C	0°C to 70°C
TLC2543I	–40°C to 85°C
TLC2543M	–55°C to 125°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	V		
Positive reference voltage, V <sub>ref+</sub> (see No	ote 2)			Vcc		V
Negative reference voltage, V <sub>ref</sub> (see N	ote 2)			0		V
Differential reference voltage, V <sub>ref+</sub> - V <sub>ref</sub>	ef – (see Note 2)		2.5	Vcc	V <sub>CC</sub> +0.1	V
Analog input voltage (see Note 2)			0		Vcc	V
High-level control input voltage, VIH		V <sub>CC</sub> = 4.5 V to 5.5 V	2			V
Low-level control input voltage, V <sub>IL</sub>		V <sub>CC</sub> = 4.5 V to 5.5 V			0.8	V
Clock frequency at I/O CLOCK			0		4.1	MHz
Setup time, address bits at DATA INPUT before I/O CLOCK↑, t <sub>SU(A)</sub> (see Figure 4)						ns
Hold time, address bits after I/O CLOCK	0			ns		
Hold time, CS low after last I/O CLOCK↓	0			ns		
Setup time, CS low before clocking in first	1.425			μs		
Pulse duration, I/O CLOCK high, twH(I/O		120			ns	
Pulse duration, I/O CLOCK low, t <sub>WL(I/O)</sub>			120			ns
Transition time, I/O CLOCK high to low, to			1	μs		
Transition time, DATA INPUT and CS, tt(			10	μs		
	TLC25430		0		70	
Operating free-air temperature, TA	TLC2543I		-40		85	°C
	TLC2543N	Л	-55		125	

NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (111111111111), while input voltages less than that applied to REF- convert as all zeros (000000000000).

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NOTE 1: All voltage values are with respect to the GND terminal with REF - and GND wired together (unless otherwise noted).

<sup>3.</sup> To minimize errors caused by noise at the CS input, the internal circuitry waits for a setup time after CS↓ before responding to control input signals. No attempt should be made to clock in an address until the minimum CS setup time has elapsed.

<sup>4.</sup> This is the time required for the clock input signal to fall from V<sub>IL</sub>max or to rise from V<sub>IL</sub>max to V<sub>IL</sub>max to V<sub>IL</sub>max. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μs for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.



# electrical characteristics over recommended operating free-air temperature range, $V_{CC} = V_{ref+} = 4.5 \text{ V}$ to 5.5 V, $f_{(I/O\ CLOCK)} = 4.1 \text{ MHz}$ (unless otherwise noted)

PARAMETER			TEST CO.	TLC2543C, TLC2543I			UNIT	
			TEST CONDITIONS		MIN	TYP†	MAX	UNII
V/011	High-level output voltage		$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = -1.6 mA	2.4			V
VOH	riigii-ievei outpui	voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I <sub>OH</sub> = -20 μA	V <sub>CC</sub> -0.1			٧
Vai	Low-level output voltage		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 1.6 mA			0.4	V
VOL Low-level outp		voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I <sub>OL</sub> = 20 μA			0.1	
, High-impedance off-		off-state output	$V_O = V_{CC}$	CS at V <sub>CC</sub>		1	2.5	
loz	current		$V_{O} = 0,$	CS at V <sub>CC</sub>		1	-2.5	μΑ
lіН	High-level input current		$V_I = V_{CC}$			1	2.5	μΑ
I <sub>I</sub> L	Low-level input current		V <sub>I</sub> = 0			1	-2.5	μΑ
ICC	Operating supply current		CS at 0 V			1	2.5	mA
I <sub>CC(PD)</sub>	Power-down current		For all digital inputs, $0 \le V_I \le 0.5 \text{ V or } V_I \ge V_{CC}$	– 0.5 V		4	25	μΑ
	Selected channel leakage current		Selected channel at V <sub>CC</sub> ,	Unselected channel at 0 V			1	
			Selected channel at 0 V, Unselected channel at V <sub>CC</sub>	;			-1	μΑ
	Maximum static analog reference current into REF+		V <sub>ref+</sub> = V <sub>CC</sub> ,	V <sub>ref</sub> _= GND		1	2.5	μΑ
C	Input	Analog inputs				30	60	ьE
Ci	capacitance	Control inputs				5	15	pF

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

# electrical characteristics over recommended operating free-air temperature range, $V_{CC} = V_{ref+} = 4.5 \text{ V}$ to 5.5 V, $f_{(I/O\ CLOCK)} = 4.1 \text{ MHz}$ (unless otherwise noted)

PARAMETER			TEOT 00	TLC2543M				
			TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V	High lavel autout valtage		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -1.6 mA	2.4			V
VOH High-level output		i voltage	V <sub>CC</sub> = 4.5 V to 5.5 V,	I <sub>OH</sub> = -20 μA	V <sub>CC</sub> -0.1			V
Voi	Low lovel output	voltago	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 1.6 mA			0.4	V
V <sub>OL</sub> Low-level outpu		voitage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OL} = 20  \mu A$			0.1	v
, High-impedance off-state out		off-state output	$V_O = V_{CC}$	CS at V <sub>CC</sub>		1	2.5	
loz	current		$V_{O} = 0,$	CS at V <sub>CC</sub>		1	-2.5	μΑ
l <sub>IH</sub>	High-level input current		$V_I = V_{CC}$			1	10	μΑ
I <sub>Ι</sub> L	Low-level input current		V <sub>I</sub> = 0			1	-10	μΑ
Icc	Operating supply current		CS at 0 V			1	10	mA
ICC(PD)	Power-down current		For all digital inputs, $0 \le V_I \le 0.5 \text{ V or } V_I \ge V_{CC}$	– 0.5 V		4	25	μА
	Selected channel leakage current		Selected channel at V <sub>CC</sub> ,	Unselected channel at 0 V			10	
			Selected channel at 0 V, Unselected channel at V <sub>C</sub> (	2			-10	μΑ
	Maximum static analog reference current into REF+		V <sub>ref+</sub> = V <sub>CC</sub> ,	V <sub>ref</sub> _= GND		1	2.5	μΑ
C.	Input	Analog inputs				30	60	~F
( ):	capacitance	Control inputs				5	15	pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



## operating characteristics over recommended operating free-air temperature range, $V_{CC} = V_{ref+} = 4.5 \text{ V}$ to 5.5 V, $f_{(I/O\ CLOCK)} = 4.1 \text{ MHz}$

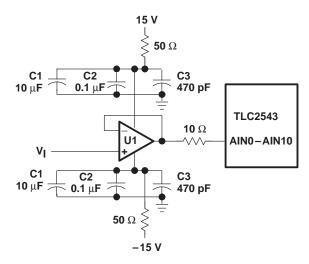
	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
EL	Linearity error (see Note 5)	See Figure 2			±1	LSB
E <sub>D</sub>	Differential linearity error	See Figure 2			±1	LSB
EO	Offset error (see Note 6)	See Note 2 and Figure 2			±1.5	LSB
E <sub>G</sub>	Gain error (see Note 6)	See Note 2 and Figure 2			±1	LSB
ET	Total unadjusted error (see Note 7)				±1.75	LSB
		DATA INPUT = 1011		2048		
	Self-test output code (see Table 3 and Note 8)	DATA INPUT = 1100		0		]
		DATA INPUT = 1101		4095		
t <sub>conv</sub>	Conversion time	See Figures 9-14		8	10	μs
t <sub>C</sub>	Total cycle time (access, sample, and conversion)	See Figures 9–14 and Note 9			10 + total I/O CLOCK periods + td(I/O-EOC)	μs
<sup>t</sup> acq	Channel acquisition time (sample)	See Figures 9-14 and Note 9	4		12	I/O CLOCK periods
t <sub>V</sub>	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 6	10			ns
td(I/O-DATA)	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 6			150	ns
td(I/O-EOC)	Delay time, last I/O CLOCK↓ to EOC↓	See Figure 7		1.5	2.2	μs
td(EOC-DATA)	Delay time, EOC↑ to DATA OUT (MSB/LSB)	See Figure 8			100	ns
tPZH, tPZL	Enable time, CS↓ to DATA OUT (MSB/LSB driven)	See Figure 3		0.7	1.3	μs
tPHZ, tPLZ	Disable time, CS↑ to DATA OUT (high impedance)	See Figure 3		70	150	ns
tr(EOC)	Rise time, EOC	See Figure 8		15	50	ns
t <sub>f</sub> (EOC)	Fall time, EOC	See Figure 7		15	50	ns
tr(bus)	Rise time, data bus	See Figure 6		15	50	ns
t <sub>f</sub> (bus)	Fall time, data bus	See Figure 6		15	50	ns
td(I/O-CS)	Delay time, last I/O CLOCK↓ to $\overline{\text{CS}}$ ↓ to abort conversion (see Note 10)				5	μs

<sup>†</sup> All typical values are at  $T_A = 25$ °C.

NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (111111111111), while input voltages less than that applied to REF- convert as all zeros (000000000000).

- 5. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
- 6. Gain error is the difference between the actual midstep value and the nominal midstep value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero. Offset error is the difference between the actual midstep value and the nominal midstep value at the offset point.
- 7. Total unadjusted error comprises linearity, zero-scale, and full-scale errors.
- 8. Both the input address and the output codes are expressed in positive logic.
- 9. I/O CLOCK period = 1/(I/O CLOCK frequency) (see Figure 7).
- 10. Any transitions of  $\overline{CS}$  are recognized as valid only when the level is maintained for a setup time.  $\overline{CS}$  must be taken low at ≤ 5 μs of the tenth I/O CLOCK falling edge to ensure a conversion is aborted. Between 5 μs and 10 μs, the result is uncertain as to whether the conversion is aborted or the conversion results are valid.





LOCATION	DESCRIPTION	PART NUMBER		
U1	OP27	_		
C1	10-μF 35-V tantalum capacitor	_		
C2	0.1-μF ceramic NPO SMD capacitor	AVX 12105C104KA105 or equivalent		
C3	470-pF porcelain Hi-Q SMD capacitor	Johanson 201S420471JG4L or equivalent		

Figure 1. Analog Input Buffer to Analog Inputs AIN0-AIN10

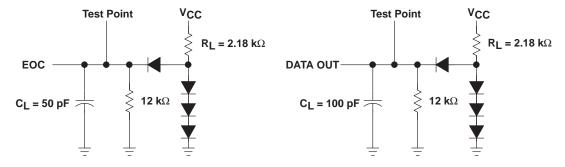


Figure 2. Load Circuits

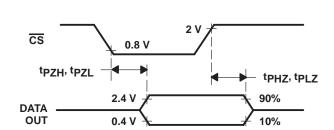


Figure 3. DATA OUT to Hi-Z Voltage Waveforms

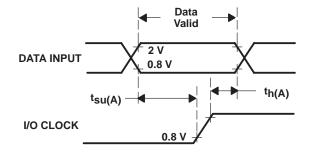
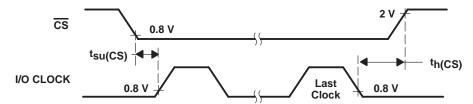


Figure 4. DATA INPUT and I/O CLOCK Voltage Waveforms





NOTE A: To ensure full conversion accuracy, it is recommended that no input signal change occurs while a conversion is ongoing.

Figure 5. CS and I/O CLOCK Voltage Waveforms

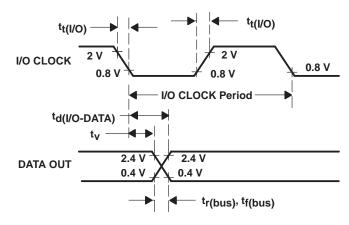


Figure 6. I/O CLOCK and DATA OUT Voltage Waveforms

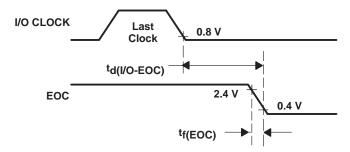


Figure 7. I/O CLOCK and EOC Voltage Waveforms

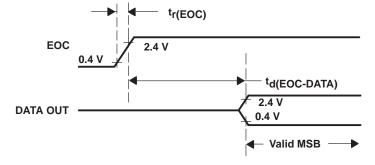
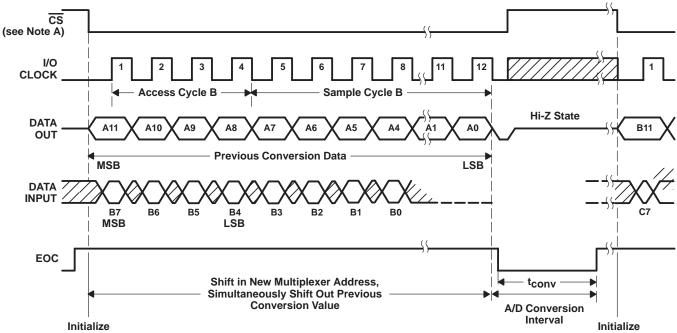


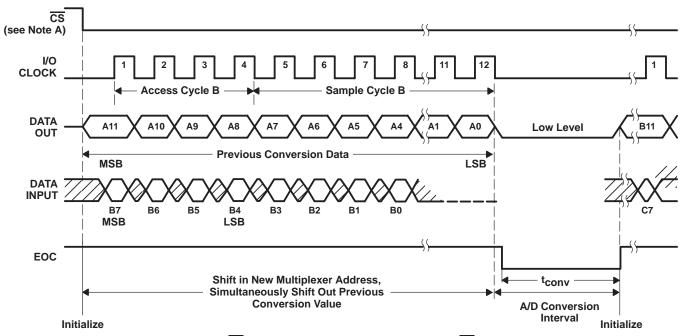
Figure 8. EOC and DATA OUT Voltage Waveforms





NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS}$ ↓ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

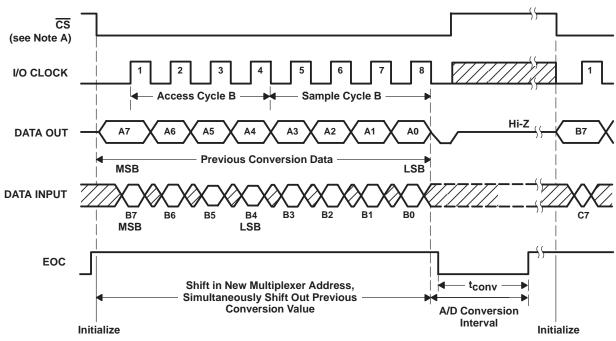
Figure 9. Timing for 12-Clock Transfer Using CS With MSB First



NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS} \downarrow$  before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

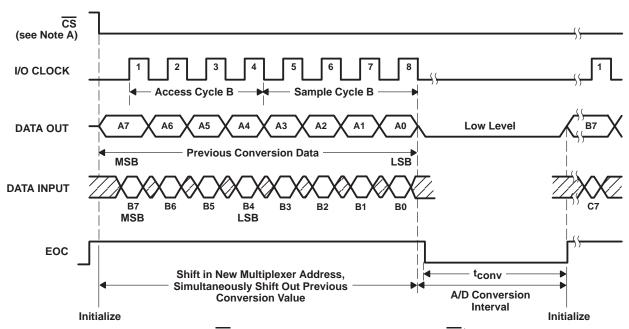
Figure 10. Timing for 12-Clock Transfer Not Using CS With MSB First





NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS}$ ↓ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

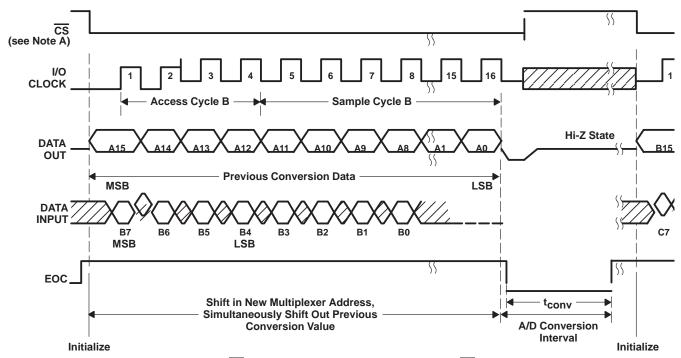
Figure 11. Timing for 8-Clock Transfer Using CS With MSB First



NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS}$ ↓ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

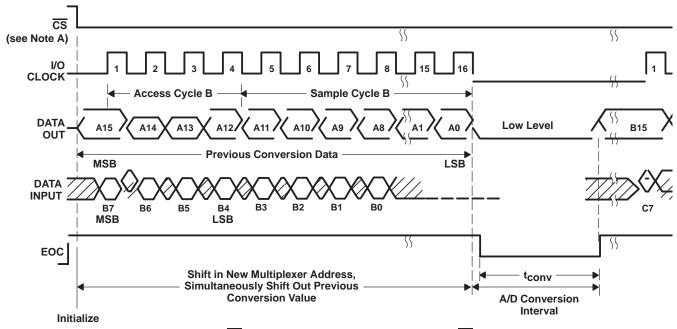
Figure 12. Timing for 8-Clock Transfer Not Using CS With MSB First





NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS}$ ↓ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

Figure 13. Timing for 16-Clock Transfer Using CS With MSB First



NOTE A: To minimize errors caused by noise at  $\overline{CS}$ , the internal circuitry waits for a setup time after  $\overline{CS}$  before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum  $\overline{CS}$  setup time has elapsed.

Figure 14. Timing for 16-Clock Transfer Not Using CS With MSB First

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 8BCPZ-RL7
 AD9530BCPZ
 MAX1436BECQ+D
 MAX16924GGM/VY+
 MAX11108AVB+T
 MAX11647EUA+T
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 MCP33141D-05T-E/MS
 MCP33151D-05T-E/MS
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 MAX11137ATI+T
 MAX11136ATI+T
 MAX11612EUA+T

 MAX11212AEUB+T
 MAX11101EUB+T
 AD4001BCPZ-RL7
 MAX14002AAP+T
 MCP33141-05T-E/MS
 MAX11636EEE+T
 MCP33141D-10T-E/MS

 10T-E/MS
 MCP33151-05T-E/MS
 MCP33151D-10T-E/MS
 MAX11259AWX+T
 AD7091R-5BRUZ-RL7

 ADE1201ACCZ
 ADE1202ACCZ
 LTC1864CS8#PBF
 LTC2418CGNPBF
 LTC2433-1IMS#PBF
 LTC2442CGPBF
 LTC2400CS8#PBF

 LTC2414CGNPBF
 TC7109ACKW
 TC7109CLW
 TC7109CLW
 TC7109CLW